



1 | 2

NOTES :

1. MATERIAL

- i) HOUSING : HIGH TEMPERATURE THERMOPLASTIC UL94V-0
- ii) TERMINAL : COPPER ALLOY
- iii) HOLD DOWN : COPPER ALLOY

2. FINISH

- i) TERMINAL : Au PLATING AT CONTACT POINT

MATT TIN PLATING 100u" MIN AT SOLDER TAIL WITH NICKEL 50u" MIN UNDERPLATE.

- ii) HOLD DOWN : MATT TIN PLATING.

MATT TIN PLATING 100u" MIN AT SOLDER TAIL WITH NICKEL 50u" MIN UNDERPLATE.

- 3. THE HOUSING WILL WITHSTAND EXPOSURE TO 260 DEGREE C PEAK TEMPERATURE FOR 10 SECONDS IN A CONNECTION, INFREA RED, OR VAPOR PHASE REFLOW OVEN.

4. Packaging spec. GS-14-840.

- 5. Product Spec. GS-12-194.

- 6. Product Spec. 110-634

10089036- 0 X X X X LEAD FREE

LEAD FREE

BLANK: SPEC AS NOTE 5

J: SPEC AS NOTE 6

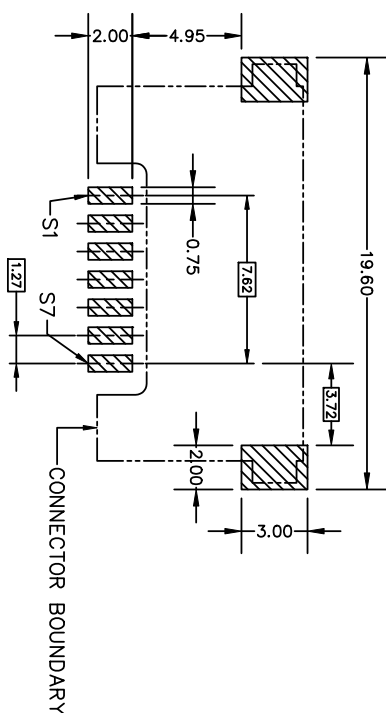
1: G/F PLATING AT CONTACT

2: 15U" GOLD AT CONTACT

3: 30U" GOLD AT CONTACT

0: T & R PACKING WITH PICK UP CAP

3 |



RECOMMENDED MOUNTING LAYOUT
RECOMMENDED PCB T: 1.6mm
TOLERANCE UNLESS OTHERWISE ±0.1mm

4

B

1 | 2

mat'l. code		tolerances unless otherwise specified		CUSTOMER COPY		FCI		www.fciconnect.com	
ltr	ecn no.	dr	date	linear	projection	title	product family	code	code
A	108-1179	S.LIN	10/30/08	.XX ± 0.25	MM	S-ATA SIGNAL PLUG	SATA	TWN	
B	108-1179	S.LIN	11/14/08	.XXX ± 0.10	MM	SMT RA TYPE ASSY	SATA	sheet	
C	109-1007	S.LIN	01/21/09	0° ±2°	MM		SATA	2 of	
sheet index	revision	sheet	sheet	sheet	sheet	sheet	sheet	sheet	sheet

3 |

ACAD

4